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### (54) LIQUID-COOLING HEAT DISSIPATION PLATE WITH UNEQUAL HEIGHT PIN-FINS AND ENCLOSED LIQUID-COOLING COOLER HAVING THE SAME

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#### (57)ABSTRACT

A liquid-cooling heat dissipation plate with unequal height pin-fins and an enclosed liquid-cooling cooler having the same are provided. The liquid-cooling heat dissipation plate includes a heat dissipation plate body, a plurality of fullheight pin-fins, and a plurality of non-full-height pin-fins. The heat dissipation plate body has a first heat dissipation surface and a second heat dissipation surface that face away from each other, the first heat dissipation surface is configured to be in contact with a plurality of heat sources, and the second heat dissipation surface is configured to be in contact with a cooling fluid. The full-height and non-full-height pin-fins are formed at the second heat dissipation surface of the heat dissipation plate body. A first heat dissipation region to an Nth heat dissipation region are defined on the heat dissipation plate body along a flowing direction of the cooling fluid.

